



Form PTO-1449 DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 219.40606X00	SERIAL NO. 10/066,645
	APPLICANT Scot A. KELLAR et al.	
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U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
	AA					
	AB					
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FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AM						
	AN						
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

NB	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE
NB	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10) 534-536 (1999)
NB	AW	"Face to Face Wafer Bonding for 3D Chip Stack Fabrication to Shorten Wire Lengths", June 27-29, 2000 VMIC Conference 2000 IMIC - 200/00/0090(c)
NB	AX	"InterChip Via Technology for Vertical System Integration", Fraunhofer Institute for Reliability and Microintegration, Munich, Germany; Infineon Technologies AG, Munich, Germany; 2001 IEEE
	AY	
	AZ	
Examiner Nema Berezny		Date Considered 6/4/03